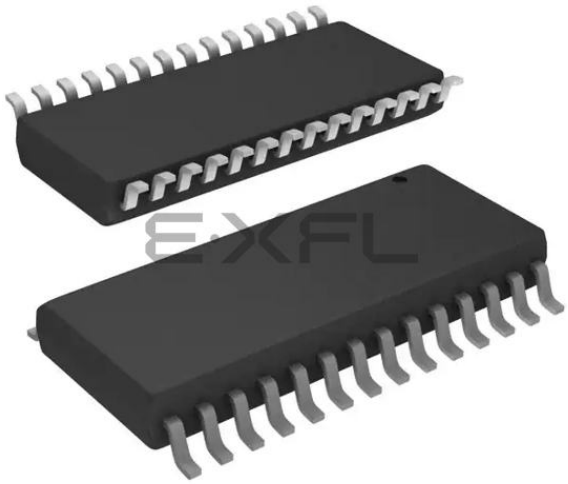

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	64 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf870-i-so

3.0 DATA EEPROM AND FLASH PROGRAM MEMORY

The Data EEPROM and FLASH Program Memory are readable and writable during normal operation over the entire VDD range. A bulk erase operation may not be issued from user code (which includes removing code protection). The data memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers (SFR).

There are six SFRs used to read and write the program and data EEPROM memory. These registers are:

- EECON1
- EECON2
- EEDATA
- EEDATH
- EEADR
- EEADRH

The EEPROM data memory allows byte read and write. When interfacing to the data memory block, EEDATA holds the 8-bit data for read/write and EEADR holds the address of the EEPROM location being accessed. The registers EEDATH and EEADRH are not used for data EEPROM access. The PIC16F870/871 devices have 64 bytes of data EEPROM with an address range from 0h to 3Fh.

The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature, as well as from chip-to-chip. Please refer to the specifications for exact limits.

The program memory allows word reads and writes. Program memory access allows for checksum calculation and calibration table storage. A byte or word write automatically erases the location and writes the new data (erase before write). Writing to program memory will cease operation until the write is complete. The program memory cannot be accessed during the write, therefore code cannot execute. During the write operation, the oscillator continues to clock the peripherals, and therefore, they continue to operate. Interrupt events will be detected and essentially “queued” until the write is completed. When the write completes, the next instruction in the pipeline is executed and the branch to the interrupt vector address will occur.

When interfacing to the program memory block, the EEDATH:EEDATA registers form a two-byte word, which holds the 14-bit data for read/write. The EEADRH:EEADR registers form a two-byte word, which holds the 13-bit address of the FLASH location being accessed. The PIC16F870/871 devices have 2K words of program FLASH with an address range from 0h to 7FFh. The unused upper bits in both the EEDATH and EEDATA registers all read as ‘0’s.

The value written to program memory does not need to be a valid instruction. Therefore, up to 14-bit numbers can be stored in memory for use as calibration parameters, serial numbers, packed 7-bit ASCII, etc. Executing a program memory location containing data that forms an invalid instruction results in a NOP.

3.1 EEADR

The address registers can address up to a maximum of 256 bytes of data EEPROM or up to a maximum of 8K words of program FLASH. However, the PIC16F870/871 have 64 bytes of data EEPROM and 2K words of program FLASH.

When selecting a program address value, the MSByte of the address is written to the EEADRH register and the LSByte is written to the EEADR register. When selecting a data address value, only the LSByte of the address is written to the EEADR register.

On the PIC16F870/871 devices, the upper two bits of the EEADR must always be cleared to prevent inadvertent access to the wrong location in data EEPROM. This also applies to the program memory. The upper five MSbits of EEADRH must always be clear during program FLASH access.

3.2 EECON1 and EECON2 Registers

The EECON1 register is the control register for configuring and initiating the access. The EECON2 register is not a physically implemented register, but is used exclusively in the memory write sequence to prevent inadvertent writes.

There are many bits used to control the read and write operations to EEPROM data and FLASH program memory. The EEPGD bit determines if the access will be a program or data memory access. When clear, any subsequent operations will work on the EEPROM data memory. When set, all subsequent operations will operate in the program memory.

Read operations only use one additional bit, RD, which initiates the read operation from the desired memory location. Once this bit is set, the value of the desired memory location will be available in the data registers. This bit cannot be cleared by firmware. It is automatically cleared at the end of the read operation. For EEPROM data memory reads, the data will be available in the EEDATA register in the very next instruction cycle after the RD bit is set. For program memory reads, the data will be loaded into the EEDATH:EEDATA registers, following the second instruction after the RD bit is set.

Write operations have two control bits, WR and WREN, and two status bits, WRERR and EEIF. The WREN bit is used to enable or disable the write operation. When WREN is clear, the write operation will be disabled. Therefore, the WREN bit must be set before executing a write operation. The WR bit is used to initiate the write operation. It also is automatically cleared at the end of the write operation. The interrupt flag EEIF is used to determine when the memory write completes. This flag must be cleared in software before setting the WR bit. For EEPROM data memory, once the WREN bit and the WR bit have been set, the desired memory address in EEADR will be erased, followed by a write of the data in EEDATA. This operation takes place in parallel with the microcontroller continuing to execute normally. When the write is complete, the EEIF flag bit will be set. For program memory, once the WREN bit and the WR bit have been set, the microcontroller will cease to execute instructions. The desired memory location pointed to by EEADRH:EEADR will be erased. Then, the data value in EEDATH:EEDATA will be programmed. When complete, the EEIF flag bit will be set and the microcontroller will continue to execute code.

The WRERR bit is used to indicate when the PIC16F870/871 devices have been reset during a write operation. WRERR should be cleared after Power-on Reset. Thereafter, it should be checked on any other RESET. The WRERR bit is set when a write operation is interrupted by a $\overline{\text{MCLR}}$ Reset, or a WDT Time-out Reset, during normal operation. In these situations, following a RESET, the user should check the WRERR bit and rewrite the memory location, if set. The contents of the data registers, address registers and EEPGD bit are not affected by either $\overline{\text{MCLR}}$ Reset, or WDT Time-out Reset, during normal operation.

REGISTER 3-1: EECON1 REGISTER (ADDRESS: 18Ch)

R/W-x	U-0	U-0	U-0	R/W-x	R/W-0	R/S-0	R/S-0
EEPGD	—	—	—	WRERR	WREN	WR	RD
bit 7							bit 0

bit 7 **EEPGD**: Program/Data EEPROM Select bit
1 = Accesses program memory
0 = Accesses data memory
(This bit cannot be changed while a read or write operation is in progress.)

bit 6-4 **Unimplemented:** Read as '0'

bit 3 **WRERR**: EEPROM Error Flag bit
1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ Reset or any WDT Reset during normal operation)
0 = The write operation completed

bit 2 **WREN**: EEPROM Write Enable bit
1 = Allows write cycles
0 = Inhibits write to the EEPROM

bit 1 **WR**: Write Control bit
1 = Initiates a write cycle. (The bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) in software.)
0 = Write cycle to the EEPROM is complete

bit 0 **RD**: Read Control bit
1 = Initiates an EEPROM read. (RD is cleared in hardware. The RD bit can only be set (not cleared) in software.)
0 = Does not initiate an EEPROM read

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

3.3 Reading the EEPROM Data Memory

Reading EEPROM data memory only requires that the desired address to access be written to the EEADR register and clear the EEPGD bit. After the RD bit is set, data will be available in the EEDATA register on the very next instruction cycle. EEDATA will hold this value until another read operation is initiated or until it is written by firmware.

The steps to reading the EEPROM data memory are:

1. Write the address to EEDATA. Make sure that the address is not larger than the memory size of the PIC16F870/871 devices.
2. Clear the EEPGD bit to point to EEPROM data memory.
3. Set the RD bit to start the read operation.
4. Read the data from the EEDATA register.

EXAMPLE 3-1: EEPROM DATA READ

```
BSF    STATUS, RP1     ;
BCF    STATUS, RP0     ;Bank 2
MOVF   ADDR, W         ;Write address
MOVWF  EEADR           ;to read from
BSF    STATUS, RP0     ;Bank 3
BCF    EECON1, EEPGD   ;Point to Data memory
BSF    EECON1, RD      ;Start read operation
BCF    STATUS, RP0     ;Bank 2

MOVF   EEDATA, W       ;W = EEDATA
```

3.4 Writing to the EEPROM Data Memory

There are many steps in writing to the EEPROM data memory. Both address and data values must be written to the SFRs. The EEPGD bit must be cleared, and the WREN bit must be set, to enable writes. The WREN bit should be kept clear at all times, except when writing to the EEPROM data. The WR bit can only be set if the WREN bit was set in a previous operation (i.e., they both cannot be set in the same operation). The WREN bit should then be cleared by firmware after the write. Clearing the WREN bit before the write actually completes will not terminate the write in progress.

Writes to EEPROM data memory must also be prefaced with a special sequence of instructions that prevent inadvertent write operations. This is a sequence of five instructions that must be executed without interruptions. The firmware should verify that a write is not in progress before starting another cycle.

The steps to write to EEPROM data memory are:

1. If step 10 is not implemented, check the WR bit to see if a write is in progress.
2. Write the address to EEADR. Make sure that the address is not larger than the memory size of the PIC16F870/871 devices.
3. Write the 8-bit data value to be programmed in the EEDATA register.
4. Clear the EEPGD bit to point to EEPROM data memory.
5. Set the WREN bit to enable program operations.
6. Disable interrupts (if enabled).
7. Execute the special five instruction sequence:
   - Write 55h to EECON2 in two steps (first to W, then to EECON2)
   - Write AAh to EECON2 in two steps (first to W, then to EECON2)
   - Set the WR bit
8. Enable interrupts (if using interrupts).
9. Clear the WREN bit to disable program operations.
10. At the completion of the write cycle, the WR bit is cleared and the EEIF interrupt flag bit is set. (EEIF must be cleared by firmware.) If step 1 is not implemented, then firmware should check for EEIF to be set, or WR to clear, to indicate the end of the program cycle.

EXAMPLE 3-2: EEPROM DATA WRITE

```
BSF   STATUS, RP1   ;
BSF   STATUS, RP0   ;Bank 3
BTFSC EECON1, WR    ;Wait for
GOTO  $-1           ;write to finish
BCF   STATUS, RP0   ;Bank 2
MOVF  ADDR, W       ;Address to
MOVWF EEADR         ;write to
MOVF  VALUE, W      ;Data to
MOVWF EEDATA        ;write
BSF   STATUS, RP0   ;Bank 3
BCF   EECON1, EEPGD ;Point to Data memory
BSF   EECON1, WREN  ;Enable writes
                    ;Only disable interrupts
BCF   INTCON, GIE   ;if already enabled,
                    ;otherwise discard
MOVLW 0x55          ;Write 55h to
MOVWF EECON2        ;EECON2
MOVLW 0xAA          ;Write AAh to
MOVWF EECON2        ;EECON2
BSF   EECON1, WR    ;Start write operation
                    ;Only enable interrupts
BSF   INTCON, GIE   ;if using interrupts,
                    ;otherwise discard
BCF   EECON1, WREN  ;Disable writes
```

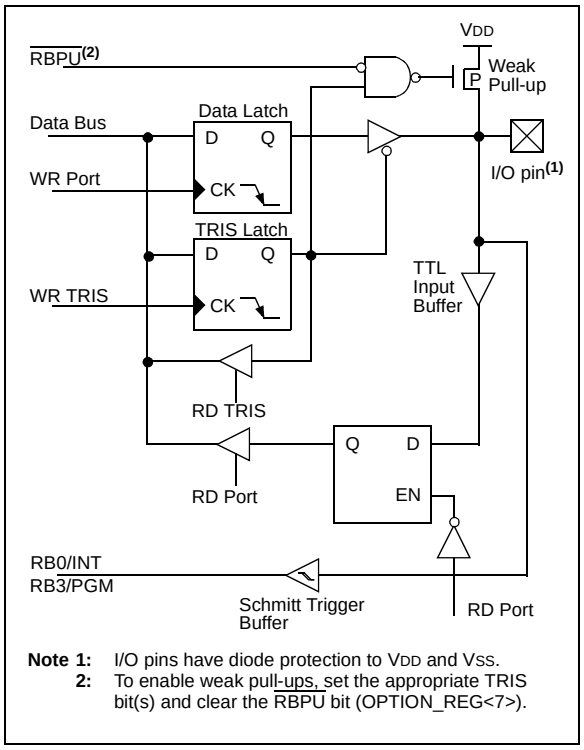
4.2 PORTB and the TRISB Register

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

Three pins of PORTB are multiplexed with the Low Voltage Programming function: RB3/PGM, RB6/PGC and RB7/PGD. The alternate functions of these pins are described in the Special Features Section.

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit RBPU (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 4-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

Four of PORTB's pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

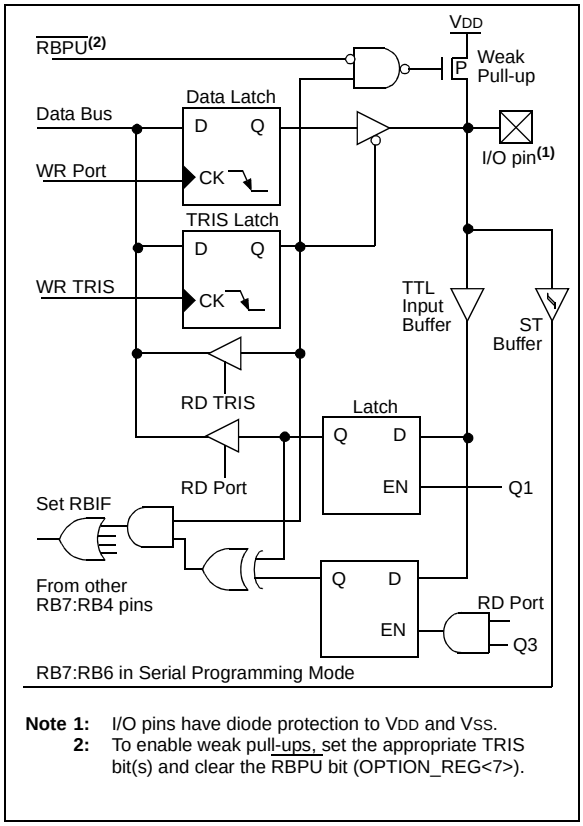
The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins, allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, *"Implementing Wake-up on Key Stroke"* (AN552).

RB0/INT is an external interrupt input pin and is configured using the INTEDG bit (OPTION_REG<6>).

RB0/INT is discussed in detail in Section 11.10.1.

FIGURE 4-4: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

4.5 PORTE and TRISE Register

This section is not applicable to the PIC16F870.

PORTE has three pins, RE0/$\overline{RD}$/AN5, RE1/$\overline{WR}$/AN6 and RE2/$\overline{CS}$/AN7, which are individually configurable as inputs or outputs. These pins have Schmitt Trigger input buffers.

I/O PORTE becomes control inputs for the microprocessor port when bit PSPMODE (TRISE<4>) is set. In this mode, the user must make sure that the TRISE<2:0> bits are set (pins are configured as digital inputs). Ensure ADCON1 is configured for digital I/O. In this mode, the input buffers are TTL.

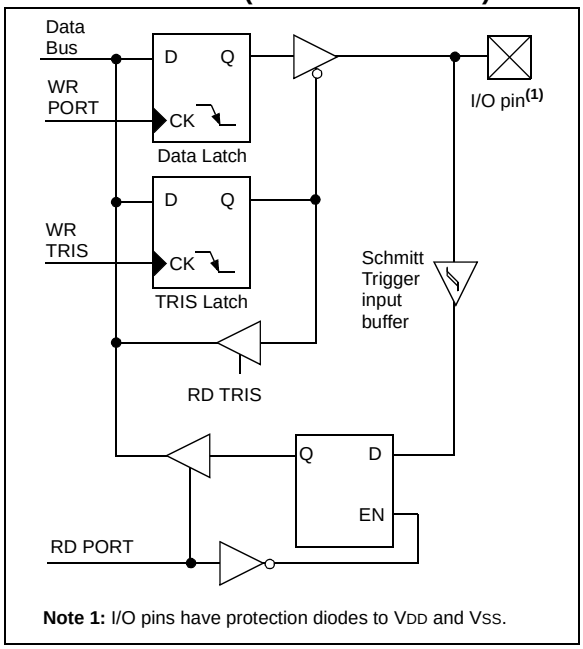
Register 4-1 shows the TRISE register, which also controls the parallel slave port operation.

PORTE pins are multiplexed with analog inputs. When selected as an analog input, these pins will read as '0's.

TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note:	On a Power-on Reset, these pins are configured as analog inputs.

FIGURE 4-7: PORTE BLOCK DIAGRAM (IN I/O PORT MODE)



Note 1: I/O pins have protection diodes to VDD and VSS.

NOTES:

6.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during SLEEP and can generate an interrupt-on-overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (Section 6.4.1).

In Asynchronous Counter mode, Timer1 cannot be used as a time base for capture or compare operations.

6.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Examples 12-2 and 12-3 in the PIC® Mid-Range MCU Family Reference Manual (DS33023) show how to read and write Timer1 when it is running in Asynchronous mode.

6.5 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit, T1OSCEN (T1CON<3>). The oscillator is a low power oscillator, rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for use with a 32 kHz crystal. Table 6-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 6-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq.	C1	C2
LP	32 kHz	33 pF	33 pF
	100 kHz	15 pF	15 pF
	200 kHz	15 pF	15 pF
These values are for design guidance only.			
Crystals Tested:			
32.768 kHz	Epson C-001R32.768K-A		± 20 PPM
100 kHz	Epson C-2 100.00 KC-P		± 20 PPM
200 kHz	STD XTL 200.000 kHz		± 20 PPM

Note 1: Higher capacitance increases the stability of oscillator, but also increases the start-up time.

2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

6.6 Resetting Timer1 Using a CCP Trigger Output

If the CCP1 module is configured in Compare mode to generate a “special event trigger” (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1.

Note: The special event triggers from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

Timer1 must be configured for either Timer or Synchronized Counter mode to take advantage of this feature. If Timer1 is running in Asynchronous Counter mode, this RESET operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPRH:CCPRL register pair effectively becomes the period register for Timer1.

7.1 Timer2 Prescaler and Postscaler

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device RESET (POR, $\overline{\text{MCLR}}$ Reset, WDT Reset, or BOR)

TMR2 is not cleared when T2CON is written.

7.2 Output of TMR2

The output of TMR2 (before the postscaler) is fed to the SSP module, which optionally uses it to generate shift clock.

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER2 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	0000 -000	0000 -000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	0000 -000	0000 -000
11h	TMR2	Timer2 Module's Register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
92h	PR2	Timer2 Period Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer2 module.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F870; always maintain these bits clear.

When setting up an Asynchronous Reception, follow these steps:

1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, set bit BRGH (Section 9.1).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, then set enable bit RCIE.
4. If 9-bit reception is desired, then set bit RX9.
5. Enable the reception by setting bit CREN.
6. Flag bit RCIF will be set when reception is complete and an interrupt will be generated if enable bit RCIE is set.
7. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading the RCREG register.
9. If any error occurred, clear the error by clearing enable bit CREN.
10. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 9-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	R0IF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	0000 -000	0000 -000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for asynchronous reception.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F870; always maintain these bits clear.

9.4 USART Synchronous Slave Mode

Synchronous Slave mode differs from the Master mode in the fact that the shift clock is supplied externally at the RC6/TX/CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

9.4.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.
b) The second word will remain in TXREG register.
c) Flag bit TXIF will not be set.
d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.
e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

When setting up a Synchronous Slave Transmission, follow these steps:

1. Enable the synchronous slave serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. Clear bits CREN and SREN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting enable bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.
8. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 9-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	R0IF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	0000 -000	0000 -000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	0000 -000	0000 -000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used for synchronous slave transmission.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F870; always maintain these bits clear.

NOTES:

REGISTER 10-2: ADCON1 REGISTER (ADDRESS: 9Fh)

U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified. 6 Most Significant bits of ADRESH are read as '0'.
0 = Left justified. 6 Least Significant bits of ADRESL are read as '0'.

bit 6-4 **Unimplemented:** Read as '0'

bit 3-0 **PCFG3:PCFG0**: A/D Port Configuration Control bits:

PCFG3: PCFG0	AN7(1) RE2	AN6(1) RE1	AN5(1) RE0	AN4 RA5	AN3 RA3	AN2 RA2	AN1 RA1	AN0 RA0	VREF+	VREF-	CHAN/ Refs(2)
0000	A	A	A	A	A	A	A	A	VDD	VSS	8/0
0001	A	A	A	A	VREF+	A	A	A	RA3	VSS	7/1
0010	D	D	D	A	A	A	A	A	VDD	VSS	5/0
0011	D	D	D	A	VREF+	A	A	A	RA3	VSS	4/1
0100	D	D	D	D	A	D	A	A	VDD	VSS	3/0
0101	D	D	D	D	VREF+	D	A	A	RA3	VSS	2/1
011x	D	D	D	D	D	D	D	D	VDD	VSS	0/0
1000	A	A	A	A	VREF+	VREF-	A	A	RA3	RA2	6/2
1001	D	D	A	A	A	A	A	A	VDD	VSS	6/0
1010	D	D	A	A	VREF+	A	A	A	RA3	VSS	5/1
1011	D	D	A	A	VREF+	VREF-	A	A	RA3	RA2	4/2
1100	D	D	D	A	VREF+	VREF-	A	A	RA3	RA2	3/2
1101	D	D	D	D	VREF+	VREF-	A	A	RA3	RA2	2/2
1110	D	D	D	D	D	D	D	A	VDD	VSS	1/0
1111	D	D	D	D	VREF+	VREF-	D	A	RA3	RA2	1/2

A = Analog input D = Digital I/O

Note 1: These channels are not available on the PIC16F870 device.

2: This column indicates the number of analog channels available as A/D inputs and the number of analog channels used as voltage reference inputs.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D result register pair, the GO/DONE bit (ADCON0<2>) is cleared and the A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 10-1.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs.

To determine sample time, see Section 10.1. After this acquisition time has elapsed, the A/D conversion can be started.

11.2 Oscillator Configurations

11.2.1 OSCILLATOR TYPES

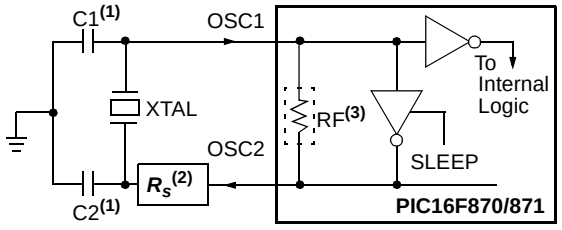
The PIC16F870/871 can be operated in four different Oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

11.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKI and OSC2/CLKO pins to establish oscillation (Figure 11-1). The PIC16F870/871 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKI pin (Figure 11-2).

FIGURE 11-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 11-1 and Table 11-2 for recommended values of C1 and C2.

2: A series resistor (R_S) may be required for AT strip cut crystals.

3: RF varies with the crystal chosen.

FIGURE 11-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

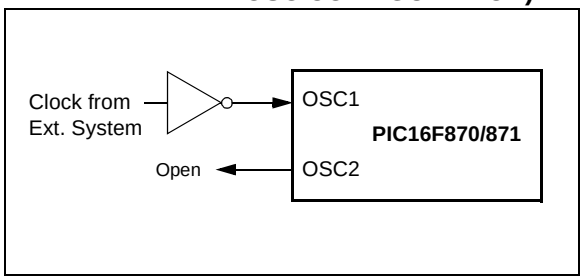


TABLE 11-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq.**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes following Table 11-2.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

FIGURE 11-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})

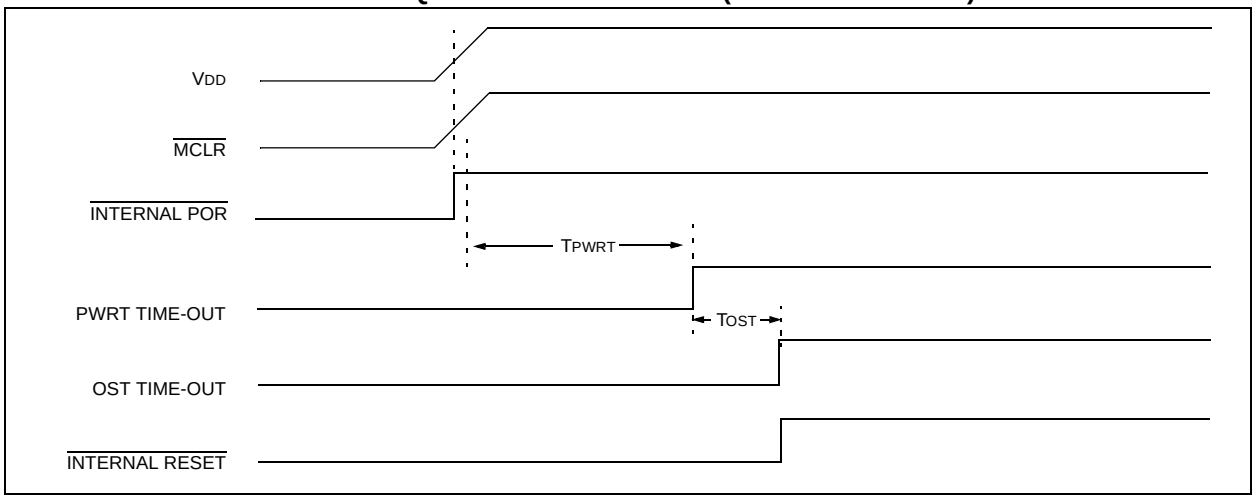


FIGURE 11-6: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

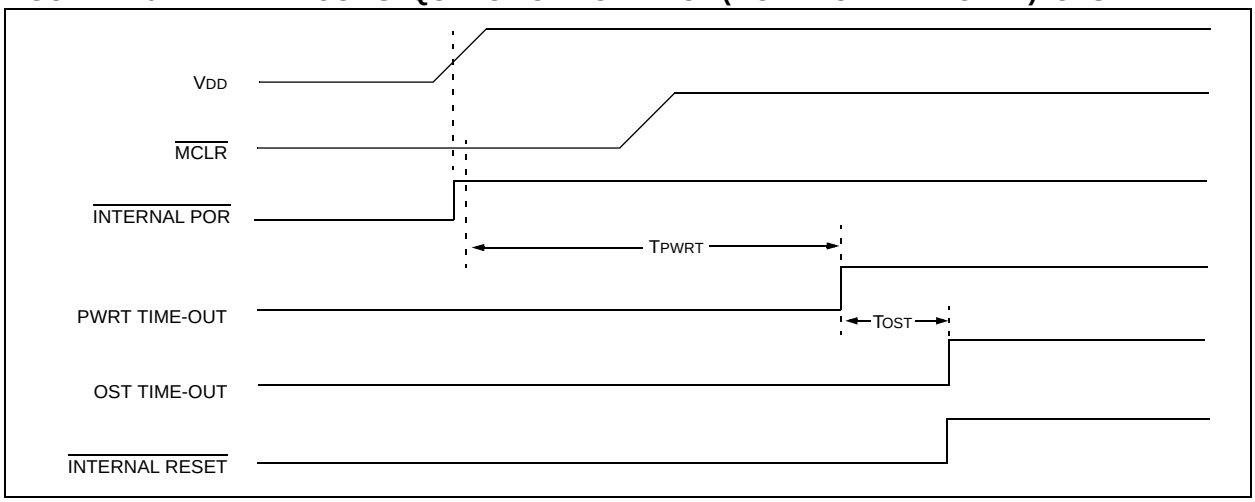
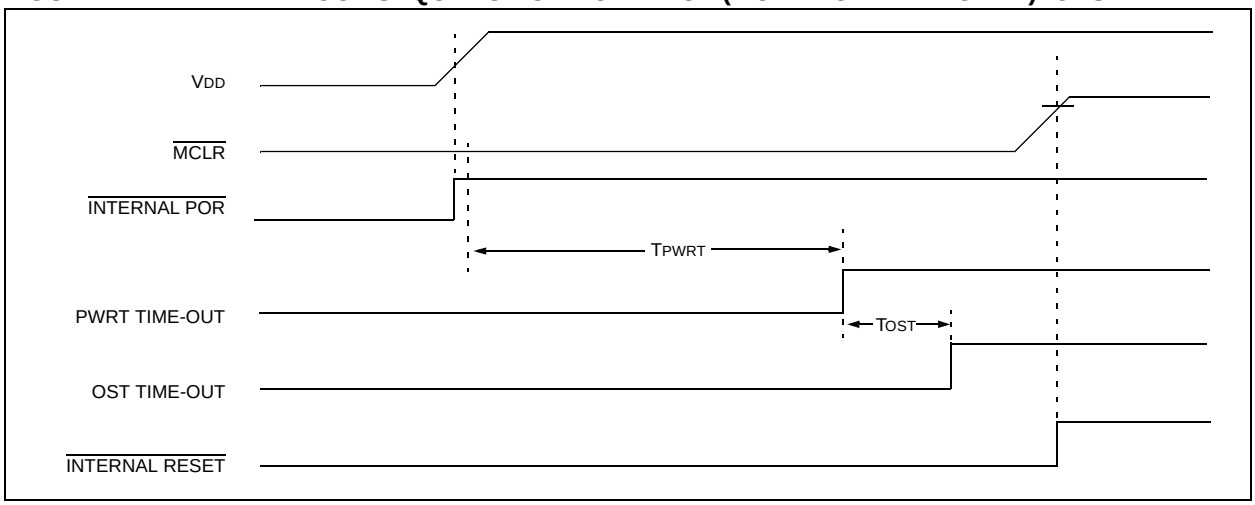


FIGURE 11-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2



14.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$. and RA4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0 to +13.25V
Voltage on RA4 with respect to Vss ..... 0 to +8.5V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) **(Note 3)** ..... 200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) **(Note 3)** ..... 200 mA
Maximum current sunk by PORTC and PORTD (combined) **(Note 3)** ..... 200 mA
Maximum current sourced by PORTC and PORTD (combined) **(Note 3)** ..... 200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (Vol \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin, rather than pulling this pin directly to V_{SS}.

3: PORTD and PORTE are not implemented on the 28-pin devices.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 14-1: PIC16FXXX VOLTAGE-FREQUENCY GRAPH

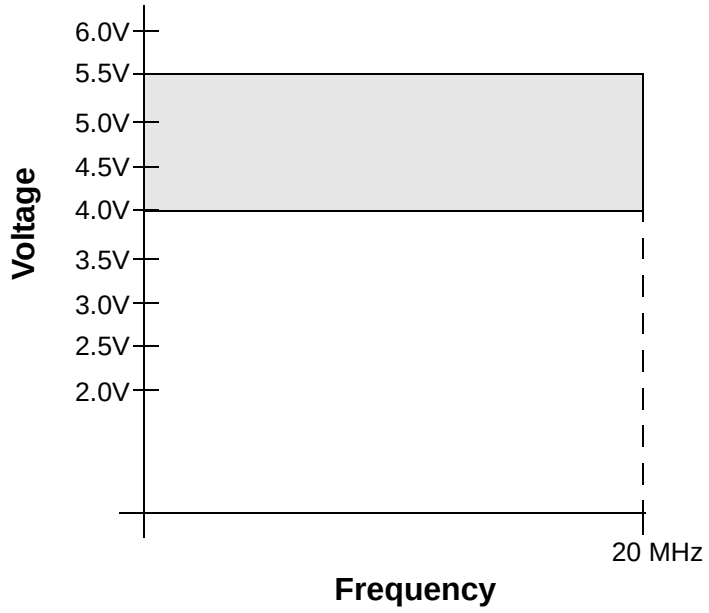
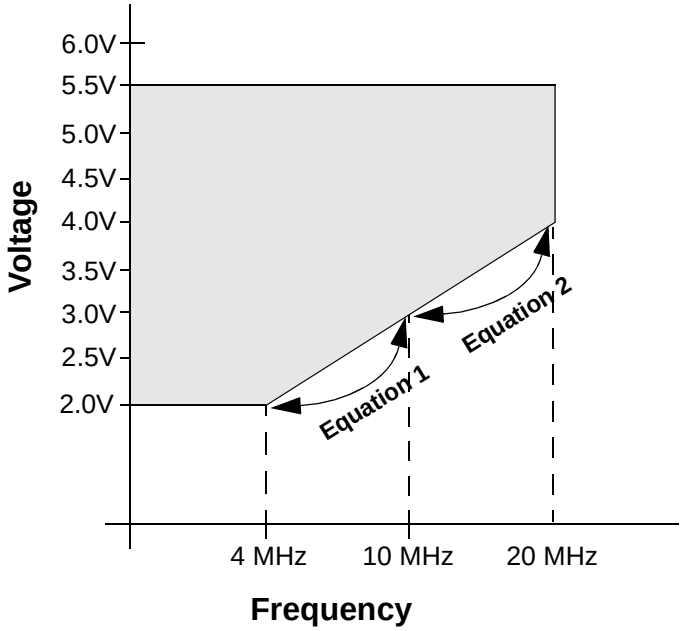


FIGURE 14-2: PIC16LFXXX VOLTAGE-FREQUENCY GRAPH



Equation 1: F_{MAX} = (6.0 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz; $V_{DDAPPMIN}$ = 2.0V - 3.0V

Equation 2: F_{MAX} = (10.0 MHz/V) ($V_{DDAPPMIN}$ – 3.0V) + 10 MHz; $V_{DDAPPMIN}$ = 3.0V - 4.0V

Note 1: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

2: F_{MAX} has a maximum frequency of 10 MHz.

14.2 DC Characteristics: PIC16F870/871 (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial Operating voltage VDD range as described in DC spec Section 14.1 and Section 14.2.				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports:					
D030		with TTL buffer	VSS	—	0.15 VDD	V	For entire VDD range
D030A			VSS	—	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031		with Schmitt Trigger buffer	VSS	—	0.2 VDD	V	
D032		$\overline{MCLR}$, OSC1 (in RC mode)	VSS	—	0.2 VDD	V	
D033		OSC1 (in XT, HS and LP)	VSS	—	0.3 VDD	V	**(Note 1)**
		Ports RC3 and RC4:					
D034		with Schmitt Trigger buffer	VSS	—	0.3 VDD	V	For entire VDD range
D034A		with SMBus	-0.5	—	0.6	V	For VDD = 4.5 to 5.5V
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8V	—	VDD	V	For entire VDD range
D041		with Schmitt Trigger buffer	0.8 VDD	—	VDD	V	For entire VDD range
D042		$\overline{MCLR}$	0.8 VDD	—	VDD	V	
D042A		OSC1 (XT, HS and LP)	0.7 VDD	—	VDD	V	**(Note 1)**
D043		OSC1 (in RC mode)	0.9 VDD	—	VDD	V	
		Ports RC3 and RC4:					
D044		with Schmitt Trigger buffer	0.7 VDD	—	VDD	V	For entire VDD range
D044A		with SMBus	1.4	—	5.5	V	for VDD = 4.5 to 5.5V
D070	IPURB	**PORTB Weak Pull-up Current**	50	250	400	µA	VDD = 5V, VPIN = VSS
	IIL	**Input Leakage Current (Notes 2, 3)**					
D060		I/O ports	—	—	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061		$\overline{MCLR}$, RA4/T0CKI	—	—	±5	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	—	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC16F870/871 be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

TABLE 14-9: PIC16F870/871 (INDUSTRIAL)
PIC16LF870/871 (INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	10-bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A07	EGN	Gain error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity(3)		—	guaranteed	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage (VREF+ – VREF-)		2.0V	—	VDD + 0.3	V	
A21	VREF+	Reference voltage High		VDD – 2.5V		VDD + 0.3V	V	Must meet spec. A20
A22	VREF-	Reference voltage Low		VSS – 0.3V		VREF+ – 2.0V	V	Must meet spec. A20
A25	VAIN	Analog input voltage		VSS – 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	Standard(**F**)	—	220	—	μA	Average current consumption when A/D is on **(Note 1)**.
			Extended(**LF**)	—	90	—	μA	
A50	IREF	VREF input current **(Note 2)**		10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 10.1.
				—	—	10	μA	During A/D Conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage, and has no missing codes.

FIGURE 15-19: TYPICAL, MINIMUM AND MAXIMUM VOL vs. IOL (VDD = 3V, -40°C TO 125°C)

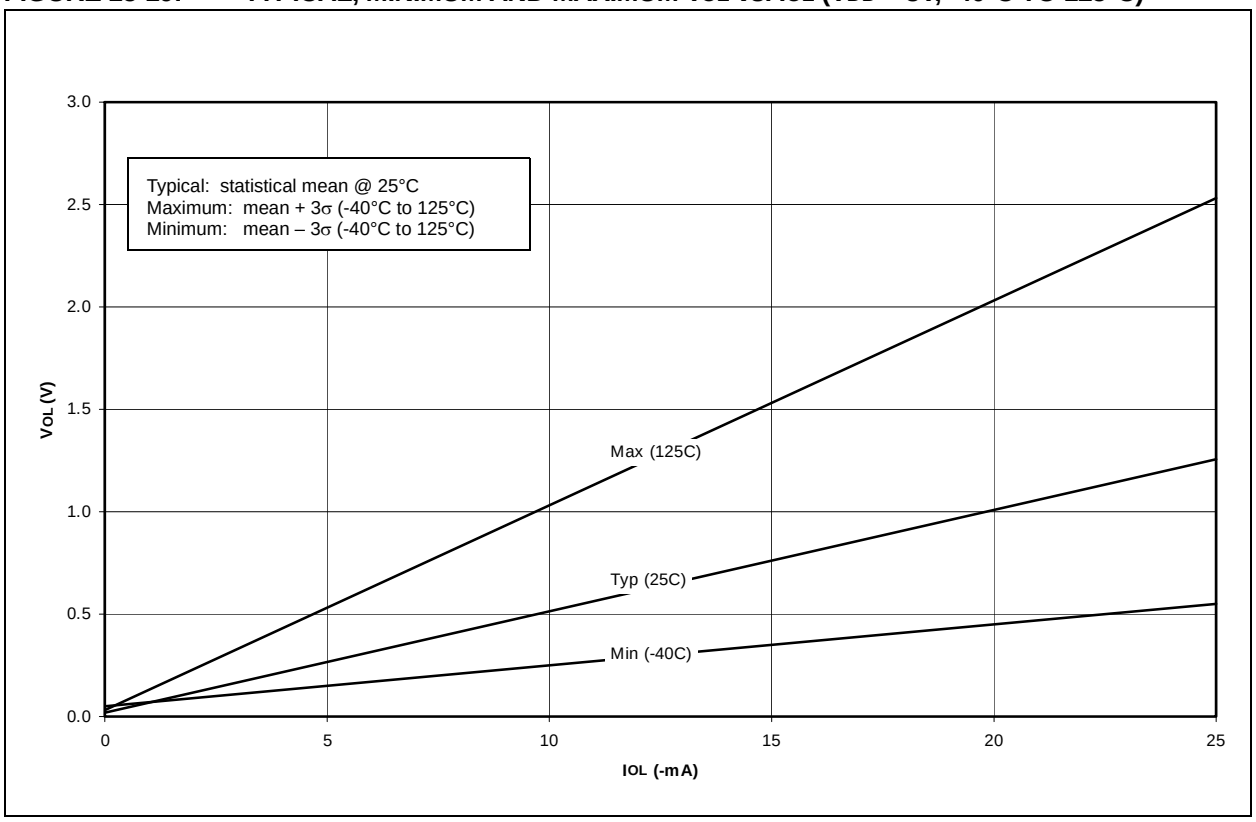
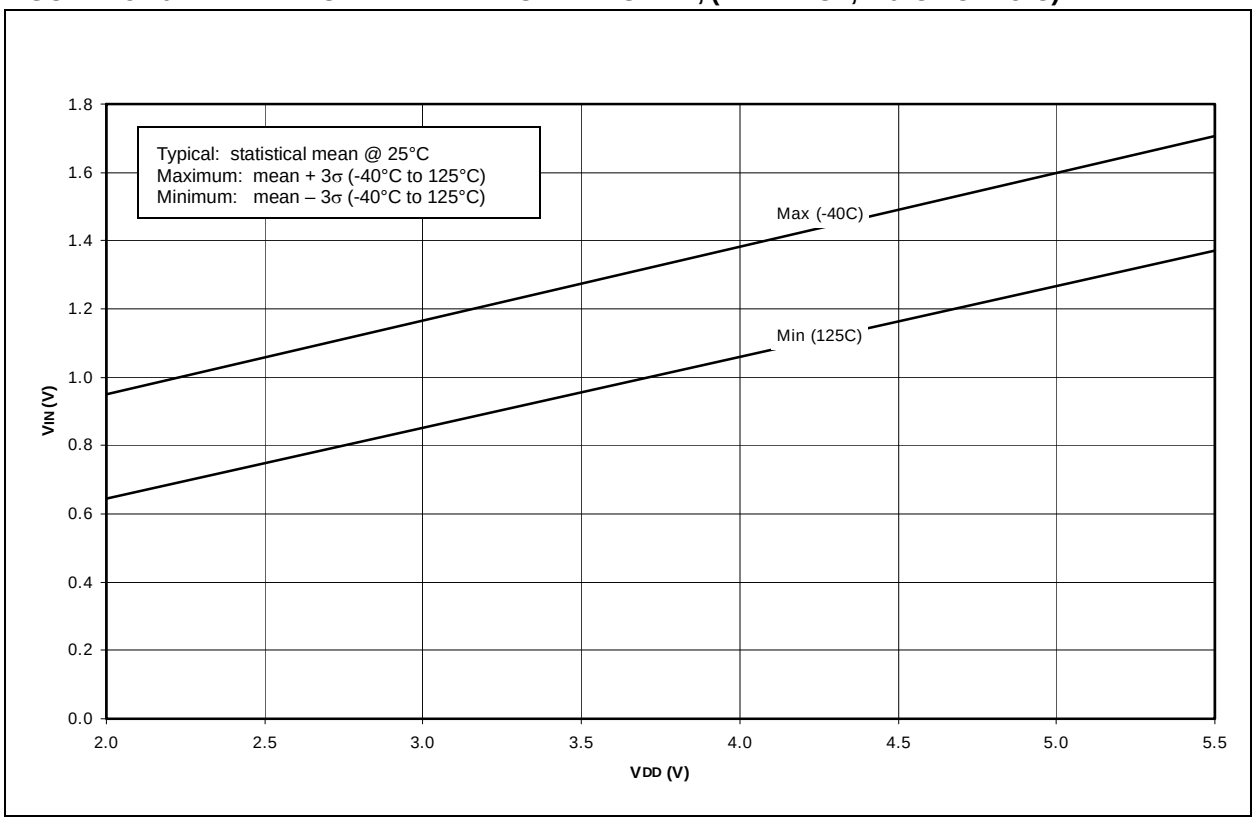


FIGURE 15-20: MINIMUM AND MAXIMUM VIN vs. VDD, (TTL INPUT, -40°C TO 125°C)



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